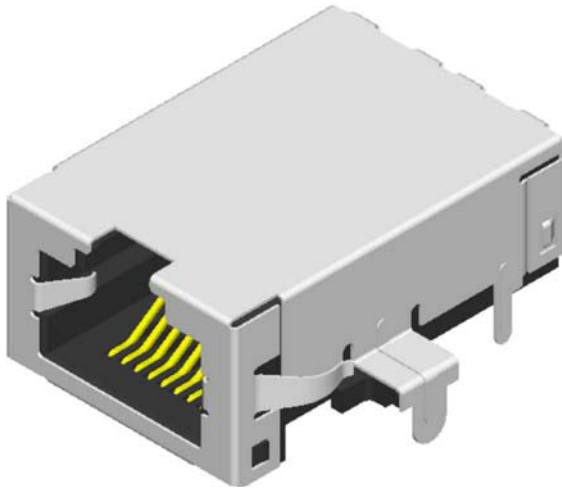


◆ Gigabit Modular Jack Dip Type



Ordering Information:

GDI27 - N3 - 09 * $\frac{A}{1}$ 300

1.Plating Options
A-50u" Gold In Contact Area

Physical:

- ◆ Plastic Housing
High Temp Thermoplastic, UL94V-0 Rated, Black Color
- ◆ Transformer Housing
Phenolic, UL94V-0 Rated, Black Color
- ◆ Terminal
Copper Alloy
- ◆ Terminal Plating
Gold Plating on Contact Area
Tin Plating on Solder Tails
Nickel Underplating Overall
- ◆ Shell
Copper Alloy
- ◆ Shell Plating
Nickel Underplating Overall
Pre-Soldering on Ground Legs

Mechanical Specifications:

- ◆ Mate Force
35.6N Max.
- ◆ Durability
1000 Cycles
- ◆ Operating Temperature Rating
0°C to +70°C

Electrical Specifications:

- ◆ Contact Resistance
20 Milliohms Max. Initial
- ◆ Dielectric Withstanding Voltage
500V per Second Max.
- ◆ Insulation Resistance
1000 Megohms Min.

Magnetic Electrical Specifications:

TEST ITEM	FREQUENCY	SPEC. REQUIREMENT (LIMIT)
Insertion Loss	0.1~1MHz	-1.1 dB MAX.
	1~65MHz	-0.5 dB MAX.
	65~100MHz	-0.8 dB MAX.
	100~125MHz	-1.2 dB MAX.
Return Loss	0.5~40MHz	-18 dB MIN.
	40~100MHz	-12+20*LOG ₁₀ (f MHz/80)
CMRR	2~100MHz	-39+19.2*LOG ₁₀ (f MHz/50)
CMR	0.1~100MHz	-30 dB MIN.
Cross-Talk	1~100MHz	-30+20*LOG ₁₀ (f MHz/100)

- ◆ Hi-pot: J To P:2250VDC/1mA/1S
J To Shield:2250VDC/1mA/1S
P To Shield:500VDC/1mA/1S

